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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	4 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LBGA
Supplier Device Package	100-FBGA (11x11)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128bfc100-4n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

MAX 7000B devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate up to 50% lower power while adding only a nominal timing delay. MAX 7000B devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000B devices can be set for 3.3 V, 2.5 V, or 1.8 V and all input pins are 3.3-V, 2.5-V, and 1.8-V tolerant, allowing MAX 7000B devices to be used in mixed-voltage systems.

MAX 7000B devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)— and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. Altera software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. Altera software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

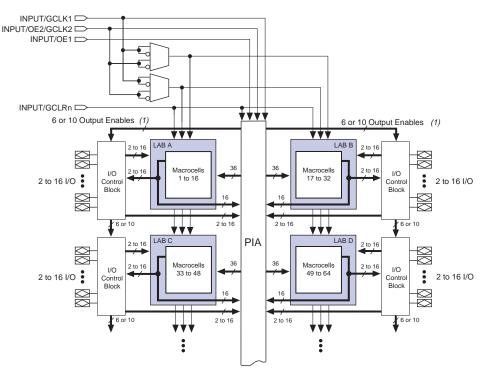
Functional Description

The MAX 7000B architecture includes the following elements:

- LABs
- Macrocells
- Expander product terms (shareable and parallel)
- PIA
- I/O control blocks

The MAX 7000B architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of MAX 7000B devices.





Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enables. EPM7512B devices have ten output enables.

Logic Array Blocks

The MAX 7000B device architecture is based on the linking of high-performance LABs. LABs consist of 16 macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- **3**6 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times

Macrocells

The MAX 7000B macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. Figure 2 shows the MAX 7000B macrocell.

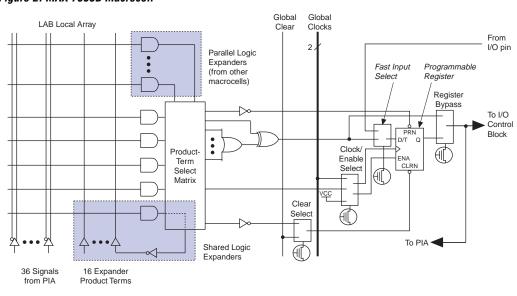


Figure 2. MAX 7000B Macrocell

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register preset, clock, and clock enable control functions.

Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the MAX+PLUS II software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

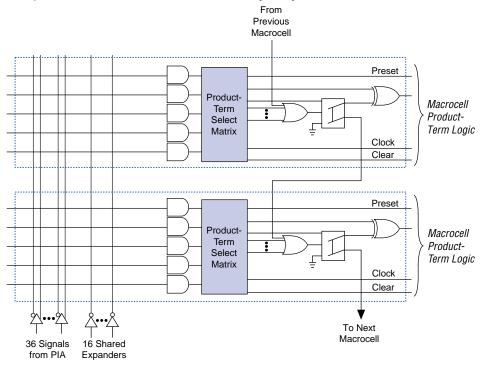
- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

Two global clock signals are available in MAX 7000B devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000B device may be set to either a high or low state. This power-up state is specified at design entry.

All MAX 7000B I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast input setup time. The input path from the I/O pin to the register has a programmable delay element that can be selected to either guarantee zero hold time or to get the fastest possible set-up time (as fast as 1.0 ns).

Figure 4. MAX 7000B Parallel Expanders



Unused product terms in a macrocell can be allocated to a neighboring macrocell.

Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000B dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a two-input AND gate, which selects a PIA signal to drive into the LAB.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000B device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- 1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- 4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- 5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000B Device

The time required to program a single MAX 7000B device in-system can be calculated from the following formula:

^t PROG	= t _{PPULSE} +	^{Cycle} ртск f _{TCK}
where:	t _{PROG} t _{PPULSE}	Programming timeSum of the fixed times to erase, program, and verify the EEPROM cells
	Cycle _{PTCK} f _{TCK}	Number of TCK cycles to program a deviceTCK frequency

The ISP times for a stand-alone verification of a single MAX 7000B device can be calculated from the following formula:

$t_{VER} = t_{VPULSE} + \frac{C_2}{2}$	^{JCle} VTCK ^f TCK
where: t_{VER} t_{VPULSE} $Cycle_{VTCK}$	= Verify time= Sum of the fixed times to verify the EEPROM cells= Number of TCK cycles to verify a device

The programming times described in Tables 4 through 6 are associated with the worst-case method using the enhanced ISP algorithm.

able 4. MAX 7000B t _{PULSE} & Cycle _{TCK} Values						
Device	Progra	mming	Stand-Alone Verification			
	t _{PPULSE} (s)	Cycle _{PTCK}	t _{VPULSE} (s)	Cycle _{VTCK}		
EMP7032B	2.12	70,000	0.002	18,000		
EMP7064B	2.12	120,000	0.002	35,000		
EMP7128B	2.12	222,000	0.002	69,000		
EMP7256B	2.12	466,000	0.002	151,000		
EMP7512B	2.12	914,000	0.002	300,000		

Tables 5 and 6 show the in-system programming and stand alone verification times for several common test clock frequencies.

Table 5. MAX 7000B In-System Programming Times for Different Test Clock Frequencies									
Device		f _{тск}							
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EMP7032B	2.13	2.13	2.15	2.19	2.26	2.47	2.82	3.52	S
EMP7064B	2.13	2.14	2.18	2.24	2.36	2.72	3.32	4.52	S
EMP7128B	2.14	2.16	2.23	2.34	2.56	3.23	4.34	6.56	S
EMP7256B	2.17	2.21	2.35	2.58	3.05	4.45	6.78	11.44	S
EMP7512B	2.21	2.30	2.58	3.03	3.95	6.69	11.26	20.40	S

Table 1. MAX 7000B Stand-Alone Verification Times for Different Test Clock Frequencies									
Device		f _{тск}							Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EMP7032B	0.00	0.01	0.01	0.02	0.04	0.09	0.18	0.36	S
EMP7064B	0.01	0.01	0.02	0.04	0.07	0.18	0.35	0.70	s
EMP7128B	0.01	0.02	0.04	0.07	0.14	0.35	0.69	1.38	s
EMP7256B	0.02	0.03	0.08	0.15	0.30	0.76	1.51	3.02	S
EMP7512B	0.03	0.06	0.15	0.30	0.60	1.50	3.00	6.00	S

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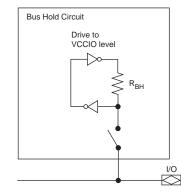
Programming with External Hardware	MAX 7000B devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.
	For more information, see the <i>Altera Programming Hardware Data Sheet</i> .
	The Altera software can use text- or waveform-format test vectors created with the Altera Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional device behavior with the results of simulation.
	Data I/O, BP Microsystems, and other programming hardware manufacturers provide programming support for Altera devices. For more information, see <i>Programming Hardware Manufacturers</i> .
IEEE Std. 1149.1 (JTAG) Boundary-Scan Support	MAX 7000B devices include the JTAG boundary-scan test circuitry defined by IEEE Std. 1149.1. Table 6 describes the JTAG instructions supported by MAX 7000B devices. The pin-out tables starting on page 59 of this data sheet show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 6. MAX 7000B	JTAG Instructions
JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, which allows the boundary-scan test data to pass synchronously through a selected device to adjacent devices during normal operation.
CLAMP	Allows the values in the boundary-scan register to determine pin states while placing the 1-bit bypass register between the TDI and TDO pins.
IDCODE	Selects the IDCODE register and places it between the TDI and TDO pins, allowing the IDCODE to be serially shifted out of TDO.
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE value to be shifted out of TDO.
ISP Instructions	These instructions are used when programming MAX 7000B devices via the JTAG ports with the MasterBlaster or ByteBlasterMV download cable, or using a Jam File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File (.svf) via an embedded processor or test equipment.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

Figure 10. Bus-Hold Circuit



PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the *PCI Local Bus Specification Revision 2.2* except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing Specifications							
Device	Specification						
	33-MHz PCI	66-MHz PCI					
EPM7032B	All speed grades	-3					
EPM7064B	All speed grades	-3					
EPM7128B	All speed grades	-4					
EPM7256B	All speed grades	-5 (1)					
EPM7512B	All speed grades	-5 (1)					

Note:

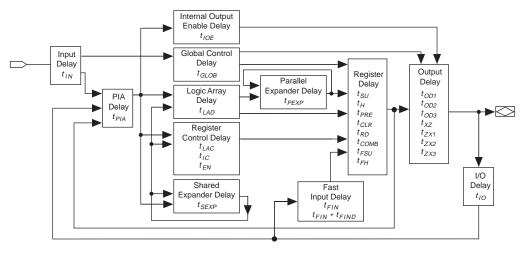
(1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

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Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(10)	2.375	2.625	V
V _{CCIO}	Supply voltage for output drivers, 3.3-V operation		3.0	3.6	V
	Supply voltage for output drivers, 2.5-V operation		2.375	2.625	V
	Supply voltage for output drivers, 1.8-V operation		1.71	1.89	V
V _{CCISP}	Supply voltage during in-system programming		2.375	2.625	V
VI	Input voltage	(3)	-0.5	3.9	V
Vo	Output voltage		0	V _{CCIO}	V
T _A	CISP Supply voltage during in-system programming Input voltage Output voltage	For commercial use	0	70	°C
		For industrial use (11)	-40	85	°C
TJ	Junction temperature	For commercial use	0	90	°C
		For industrial use (11)	-40	105	°C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

Timing Model

MAX 7000B device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 13. MAX 7000B devices have predictable internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for device-wide performance evaluation.

Figure 13. MAX 7000B Timing Model



The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 14 shows the timing relationship between internal and external delay parameters.



See *Application Note 94* (*Understanding MAX 7000 Timing*) for more information.

Table 20. EPM7032B Selectable I/O Standard Timing Adder Delays Notes (1)								
I/O Standard	Parameter	Speed Grade						Unit
		-3	8.5	-5	.0	-7	.5	
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of all LABs.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

I/O Standard	I/O Standard Parameter Speed Grade						Unit	
		-3 -5 -7 Min Max Min Max Min 0.0	7					
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of all LABs.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

I/O Standard	Parameter	Speed Grade						Unit
		-4		-	-7		-10	
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.6		0.8	ns
	Input to global clock and clear		0.3		0.6		0.8	ns
	Input to fast input register		0.2		0.4		0.5	ns
	All outputs		0.2		0.4		0.5	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.9		1.3	ns
	Input to global clock and clear		0.5		0.9		1.3	ns
	Input to fast input register		0.4		0.8		1.0	ns
	All outputs		1.2		2.3		3.0	ns
SSTL-2 Class I	Input to PIA		1.4		2.6		3.5	ns
	Input to global clock and clear		1.2		2.3		3.0	ns
	Input to fast input register		1.0		1.9		2.5	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.4		2.6		3.5	ns
	Input to global clock and clear		1.2		2.3		3.0	ns
	Input to fast input register		1.0		1.9		2.5	ns
	All outputs		-0.1		-0.2		-0.3	ns
SSTL-3 Class I	Input to PIA		1.3		2.4		3.3	ns
	Input to global clock and clear		1.0		1.9		2.5	ns
	Input to fast input register		0.9		1.7		2.3	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.3		2.4		3.3	ns
	Input to global clock and clear		1.0		1.9		2.5	ns
	Input to fast input register		0.9	1	1.7		2.3	ns
	All outputs		0.0	1	0.0		0.0	ns
GTL+	Input to PIA		1.7		3.2		4.3	ns
	Input to global clock and clear		1.7		3.2		4.3	ns
	Input to fast input register		1.6		3.0		4.0	ns
	All outputs		0.0		0.0		0.0	ns

Table 26. EPM7128B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) Note (1)									
I/O Standard	Parameter	Speed Grade Uni					Unit		
		-4		-7		-10			
		Min	Max	Min	Max	Min	Max		
PCI	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		1
			Min	Max	Min	Max	Min	Max	1
t _{IN}	Input pad and buffer delay			0.4		0.6		0.8	ns
t _{IO}	I/O input pad and buffer delay			0.4		0.6		0.8	ns
t _{FIN}	Fast input delay			1.5		2.5		3.1	ns
t _{FIND}	Programmable delay adder for fast input			1.5		1.5		1.5	ns
t _{SEXP}	Shared expander delay			1.5		2.3		3.0	ns
t _{PEXP}	Parallel expander delay			0.4		0.6		0.8	ns
t _{LAD}	Logic array delay			1.7		2.5		3.3	ns
t _{LAC}	Logic control array delay			1.5		2.2		2.9	ns
t _{IOE}	Internal output enable delay			0.1		0.2		0.3	ns
t _{OD1}	Output buffer and pad delay slow slew rate = off $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		0.9		1.4		1.9	ns
t _{OD3}	Output buffer and pad delay slow slew rate = on $V_{CCIO} = 2.5 V \text{ or } 3.3 V$	C1 = 35 pF		5.9		6.4		6.9	ns
t _{ZX1}	Output buffer enable delay slow slew rate = off $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		2.2		3.3		4.5	ns
t _{ZX3}	Output buffer enable delay slow slew rate = on $V_{CCIO} = 2.5$ V or 3.3 V	C1 = 35 pF		7.2		8.3		9.5	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		2.2		3.3		4.5	ns
t _{SU}	Register setup time		1.2		1.8		2.5		ns
t _H	Register hold time		0.6		1.0		1.3		ns
t _{FSU}	Register setup time of fast input		0.8		1.1		1.1		ns
t _{FH}	Register hold time of fast input		1.2		1.4		1.4		ns
t _{RD}	Register delay		1	0.7		1.0		1.3	ns
t _{COMB}	Combinatorial delay		1	0.3		0.4		0.5	ns
t _{IC}	Array clock delay		1	1.5		2.3		3.0	ns
t _{EN}	Register enable time		1	1.5		2.2		2.9	ns
t _{GLOB}	Global control delay		1	1.3		2.1		2.7	ns
t _{PRE}	Register preset time			1.0		1.6		2.1	ns
t _{CLR}	Register clear time		1	1.0		1.6		2.1	ns
t _{PIA}	PIA delay	(2)	1	1.7		2.6		3.3	ns
t _{LPA}	Low-power adder	(4)		2.0		3.0		4.0	ns

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) Note (1)									
I/O Standard	Parameter	Speed Grade						Unit	
		-5 -7 -10		0					
		Min	Max	Min	Max	Min	Max		
PCI	Input to PIA		0.0		0.0		0.0	ns	
	Input to global clock and clear		0.0		0.0		0.0	ns	
	Input to fast input register		0.0		0.0		0.0	ns	
	All outputs		0.0		0.0		0.0	ns	

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

The I_{CCINT} value depends on the switching frequency and the application logic. The I_{CCINT} value is calculated with the following equation:

 $I_{CCINT} =$

 $(A \times MC_{TON}) + [B \times (MC_{DEV} - MC_{TON})] + (C \times MC_{USED} \times f_{MAX} \times tog_{LC})$

The parameters in this equation are:

MC _{TON}	=	Number of macrocells with the Turbo Bit TM option turned
		on, as reported in the MAX+PLUS II Report File (.rpt)
MC _{DEV}	=	Number of macrocells in the device
MC _{USED}	=	Total number of macrocells in the design, as reported in
		the Report File
f _{MAX}	=	Highest clock frequency to the device
tog _{LC}	=	Average percentage of logic cells toggling at each clock
- 20		(typically 12.5%)
A, B, C	=	Constants, shown in Table 33

Table 33. MAX 7000B I _{CC} Equation Constants							
Device	Α	В	C				
EPM7032B	0.91	0.54	0.010				
EPM7064B	0.91	0.54	0.012				
EPM7128B	0.91	0.54	0.016				
EPM7256B	0.91	0.54	0.017				
EPM7512B	0.91	0.54	0.019				

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

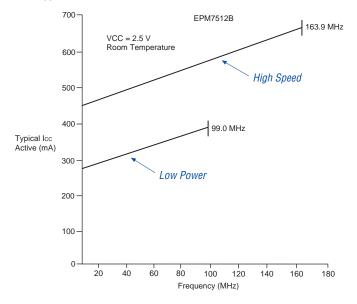


Figure 19. I_{CC} vs. Frequency for EPM7512B Devices